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PMP6025 REV E2 Bill of Materials

| Item # | Designator | Quantity | Value | PartNumber | Manufacturer | Description | PackageReference |
|--------|-----------------|----------|----------|------------------|---------------------------|---|---------------------|
| 1 | PCB1 | 1 | | PMP6025 | Any | Printed Circuit Board | - |
| 2 | C1 | 1 | 0.1µF | R82IC3100DQ60J | Kemet | CAP, Film, 0.1uF, 250VDC, Radial | Radial |
| 3 | C2 | 1 | 0.033µF | B32529C3333K | EPCOS Inc | CAP, Film, 0.033uF, 250VDC, Radial | Radial |
| 4 | C3 | 1 | 22µF | UVZ2A220MED | Nichicon | CAP, Alum, 22uF, 100V, +/-20%, Radial | Radial, Can |
| 5 | C5 | 1 | 47µF | UVZ1H470MED | Nichicon | CAP, Alum, 47uF, 50V, +/-20%, Radial | Radial, Can |
| 6 | C7 | 1 | 0.01uF | C1608C0G1E103J | TDK | CAP, CERM, 0.01uF, 25V, +/-5%, C0G/NP0, 0603 | 0603 |
| 7 | D1, D13 | 2 | 1.25V @ | BAS20LT1G | ON Semiconductor | Diode, Switch, 200V, 0.2A, SOT-23 | TO-236-3, SC-59, |
| | | | 200mA | | | | SOT-23-3 |
| 8 | D2, D14, D19, | 4 | 1000V | CGRM4007-G | Comchip Technology | Diode, P-N, 1000V, 1A, 3.9x1.7x1.8mm | 3.9x1.7x1.8mm |
| | D21 | | | | | | |
| 9 | D3, D4, D5, D6, | 12 | Warm | SAW8KG0B-X8Y1-HA | Seoul Semiconductor | LED SMD WARM WHITE 2700K | 3x.75x5.2mm |
| | D7, D8, D10, | | White | | | | |
| | D11, D15, D16, | | | | | | |
| | D17, D18 | | | | | | |
| 10 | D9, D12 | 2 | 900mV @ | MMSZ5268BT1G | ON Semiconductor | Diode, Zener, 82V, 500mW, SOD-123 | SOD-123 |
| | | | 10mA | | | | |
| 11 | D20 | 1 | 12V | MMBZ5242BLT1G | ON Semiconductor | Diode, Zener, 12V, 225mW, SOT-23 | SOT-23 |
| 12 | H1, H2 | 2 | | | | Machine Screw, Round, #2-56 | Screw |
| 13 | IS1, IS2, VP1, | 6 | SMT | 5016 | Keystone | Test Point, Compact, SMT | Testpoint_Keystone_ |
| | VP2, VS1, VS2 | | | | | | Compact |
| 14 | J1 | 1 | 1x6holes | | Harwin Inc | 1x6 Hole Pattern | 1x6 Header |
| 15 | J2 | 1 | | M22-2530605 | Harwin Inc | SIL VERTICAL PC TAIL PIN HEADER | 1x6 Header |
| 16 | Q1 | 1 | | AOD1N60 | Alpha & Omega | MOSFET, N-CH, 600V, 1.3A, DPAK | TO-252-3, DPak (2 |
| | | | | | Semiconductor Inc | | Leads + Tab), SC-63 |
| 17 | Q2 | 1 | 0.3V | MMST3904-7-F | Diodes Inc. | Transistor, NPN, 20V, 0.2A, SOT-323 | SOT-323 |
| 18 | R1 | 1 | 820 | CRCW1210820RJNEA | Vishay Dale | RES, 820 ohm, 5%, 0.5W, 1210 | 1210 (3225 Metric) |
| 19 | R2 | 1 | 1.50Meg | CRCW08051M50FKEA | Vishay-Dale | RES, 1.50Meg ohm, 1%, 0.125W, 0805 | 0805 |
| 20 | R3, R7 | 2 | 806k | CRCW1206806KFKEA | Vishay-Dale | RES, 806k ohm, 1%, 0.25W, 1206 | 1206 |
| 21 | R4, R6 | 2 | 1.00 | RMCF0805FT1R00 | Stackpole Electronics Inc | RES, 1.00 ohm, 1%, 0.125W, 0805 | 0805 |
| 22 | R5 | 1 | 1.40Meg | CRCW06031M40FKEA | Vishay-Dale | RES, 1.40Meg ohm, 1%, 0.1W, 0603 | 0603 |
| | R8 | 1 | 499k | CRCW1206499KFKEA | Vishay-Dale | RES, 499k ohm, 1%, 0.25W, 1206 | 1206 |
| | R9 | 1 | 200k | CRCW0805200KFKEA | Vishay-Dale | RES, 200 k, 1%, 0.125 W, 0805 | 0805 |
| 25 | R11, R12 | 2 | 10.0k | CRCW060310K0FKEA | Vishay-Dale | RES, 10.0k ohm, 1%, 0.1W, 0603 | 0603 |
| | R13 | 1 | 66.5 | CRCW080566R5FKEA | Vishay-Dale | RES, 66.5, 1%, 0.125 W, 0805 | 0805 |
| 27 | RF1 | 1 | 47 | EMC2-47RKI | TT Electronics/IRC | RES, 47, 10%, 2 W, Fusible, TH | Axial resistor |
| 28 | RV1 | 1 | 220V | ERZ-V05D221 | Panasonic | Varistor, 220V, 600A, TH | Disc 10x7mm |
| 29 | U1, U2 | 2 | | TPS92411PDBV | Texas Instruments | Switch Controlled Direct Drive Switch for Offline LED Drivers, DBV0005A | DBV0005A |
| | | | | | | | |

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